

MATERIAL DECLARATION SHEET



Material	MF - NSMF
Product Line	Multifuse
Revision Date	April 25, 2005
Revision	A
RoHS Compliant	Yes



No.	Breakdown of part (e.g. Lead, Ceramic body, coating, plating, additive)	Material/substance name (e.g. Sn alloy, Cu Copper)	Material/substance weight in grams (±0.1%)	CAS No. / Int. Identifier	Material /substance weight %	Sum (%)
1	Carbon Black	Carbon	0.0004225	1333-86-4	3.77%	3.77%
2	Copper plating	Copper	0.0008122	7440-50-8	7.24%	7.24%
3	Foil	Copper	0.0053732	7440-50-8	47.89%	50.41%
		Nickel	0.0002828	7440-02-0	2.52%	
4	PCB Foil	Copper	0.0006829	7440-50-8	6.09%	6.09%
5	Polymer	Polyethylene Homopolymer	0.0003742	9002-88-4	3.33%	3.33%
		Proprietary Additives ¹	0.0000005			
6	Prepreg	Epoxy	0.0019295		17.20%	28.68%
		Glass fiber	0.0012886		11.48%	
7	Plating	Nickel	0.0000534	7440-02-0	0.48%	0.48%
		Gold	0.0000007		0.01%	0.01%

Total weight (grams)	0.0112205	Total	100%	100%
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¹ Proprietary Additives materials contain no banned substances